

## General Description

SFGMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The low  $V_{th}$  series is specially designed to use in synchronous rectification power systems with low driving voltage.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_j(max)$	100	V
$I_D, pulse$	210	A
$R_{DS(ON) max} @ V_{GS}=10V$	10	mΩ
$Q_g$	49.9	nC

## Marking Information

Product Name	Package	Marking
SFG10R10AF	TO251	SFG10R10A

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	100	V
Gate source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_D$	70	A
Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	210	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_S$	70	A
Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	210	A
Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$	$P_D$	125	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	100	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	100			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.0		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		8.5	10.0	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=10 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		9.5	12.0	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=10 \text{ A}$
Gate-source leakage current	$I_{GSS}$			100	$\text{nA}$	$V_{GS}=20 \text{ V}$
Gate-source leakage current				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=100 \text{ V}, V_{GS}=0 \text{ V}$
Gate resistance	$R_G$		4.5		$\Omega$	$f=1 \text{ MHz}, \text{Open drain}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		2604		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=1 MHz
Output capacitance	C <sub>oss</sub>		361		pF	
Reverse transfer capacitance	C <sub>rss</sub>		6.5		pF	
Turn-on delay time	t <sub>d(on)</sub>		20.6		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, R <sub>G</sub> =2.2 Ω, I <sub>D</sub> =25 A
Rise time	t <sub>r</sub>		5		ns	
Turn-off delay time	t <sub>d(off)</sub>		51.8		ns	
Fall time	t <sub>f</sub>		9		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		49.9		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, I <sub>D</sub> =25 A
Gate-source charge	Q <sub>gs</sub>		6.5		nC	
Gate-drain charge	Q <sub>gd</sub>		12.4		nC	
Gate plateau voltage	V <sub>plateau</sub>		3.4		V	

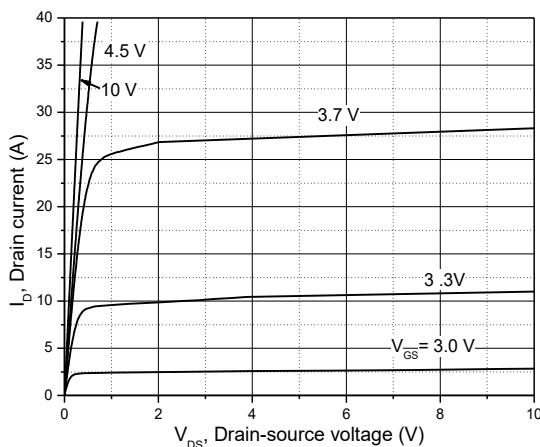
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =12 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		60.4		ns	V <sub>R</sub> =50 V, I <sub>S</sub> =12 A, di/dt=100 A/μs
Reverse recovery charge	Q <sub>rr</sub>		106.1		nC	
Peak reverse recovery current	I <sub>rrm</sub>		3		A	

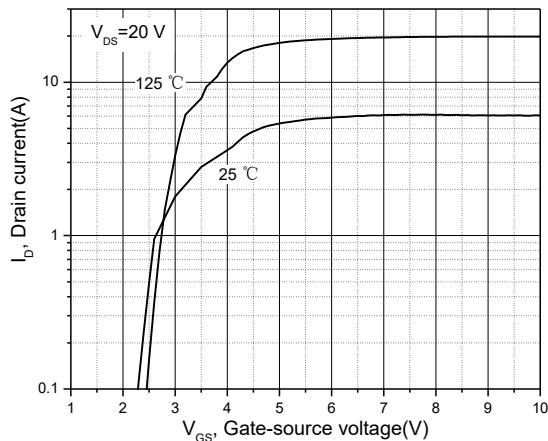
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=50 V, V<sub>GS</sub>=10 V, L=0.3 mH, starting T<sub>j</sub>=25 °C.

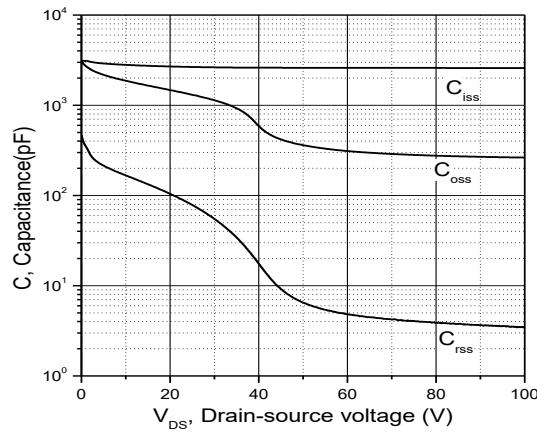
### Electrical Characteristics Diagrams



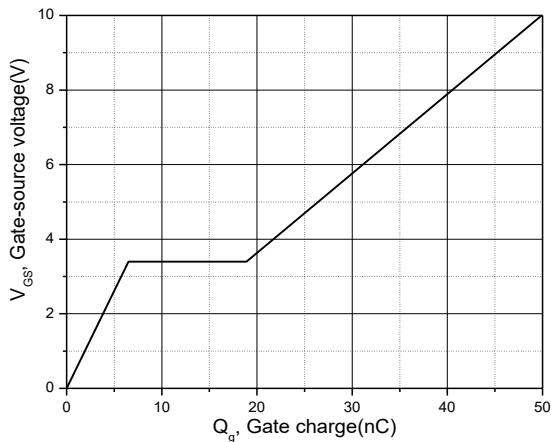
**Figure 1. Typ. output characteristics**



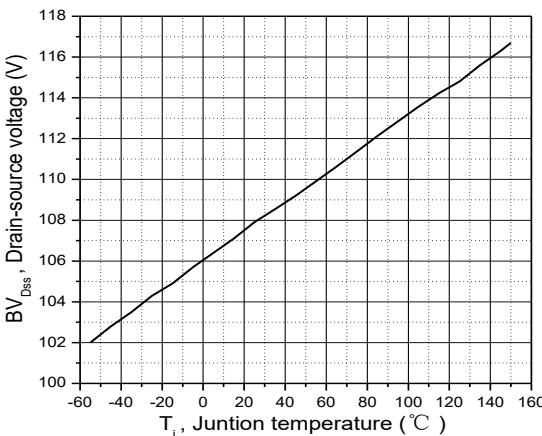
**Figure 2. Typ. transfer characteristics**



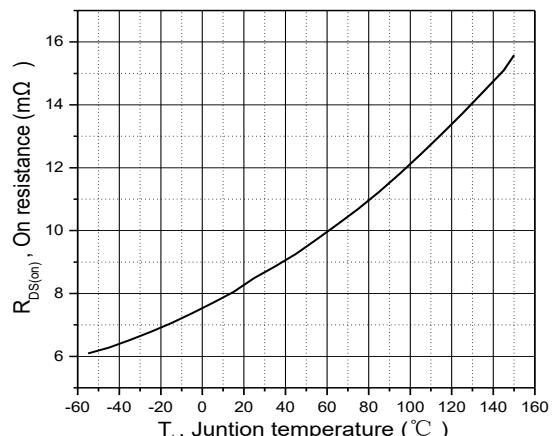
**Figure 3. Typ. capacitances**



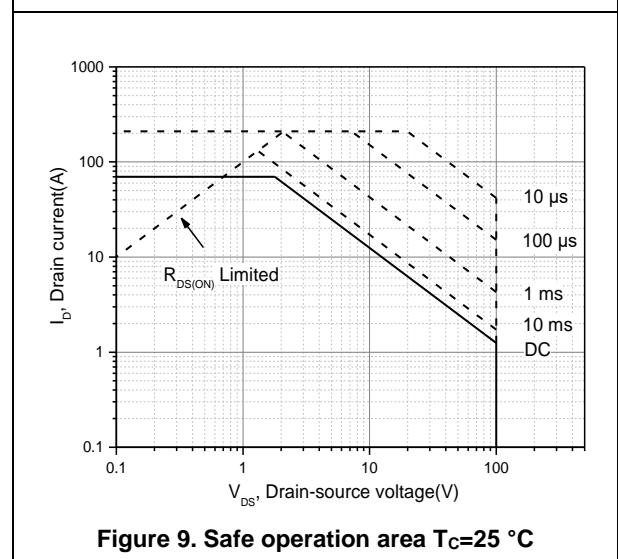
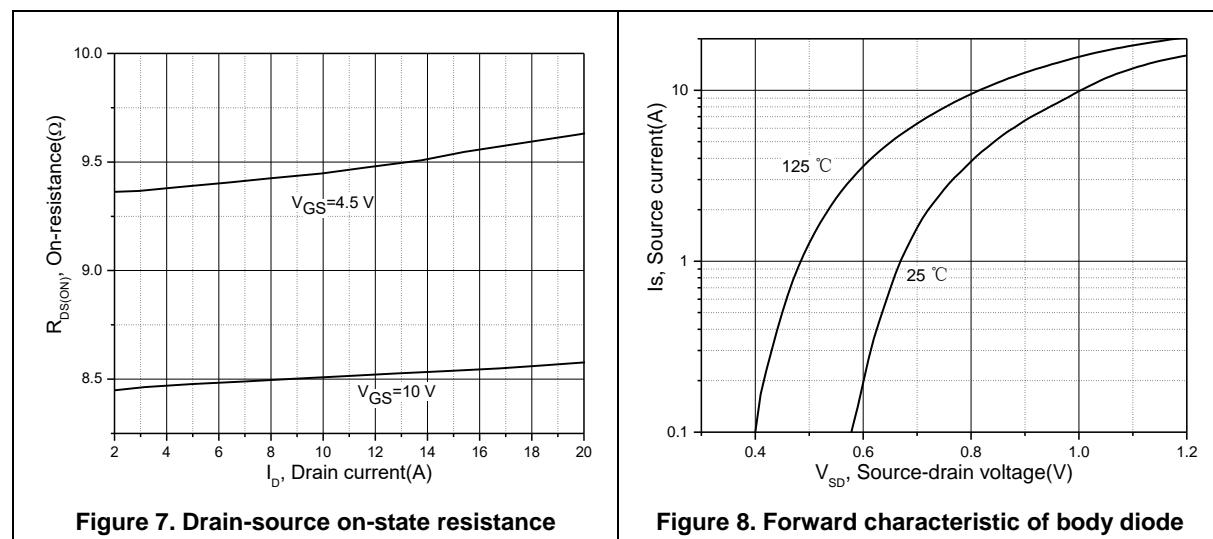
**Figure 4. Typ. gate charge**



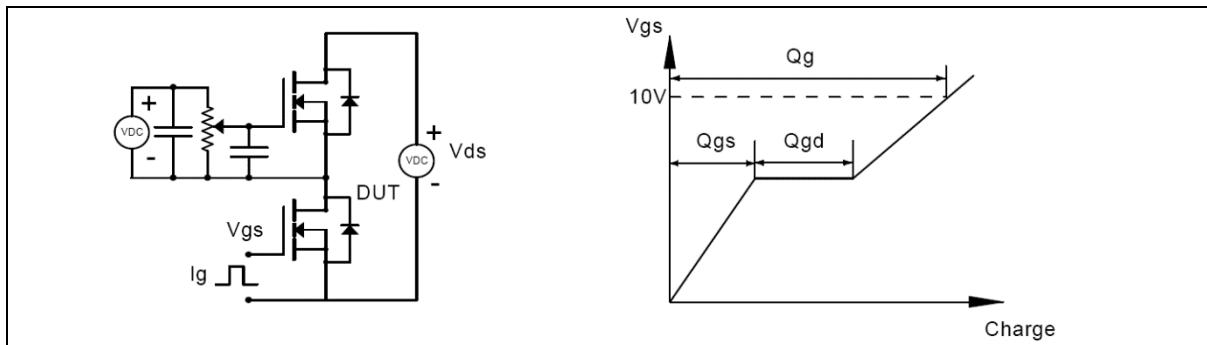
**Figure 5. Drain-source breakdown voltage**



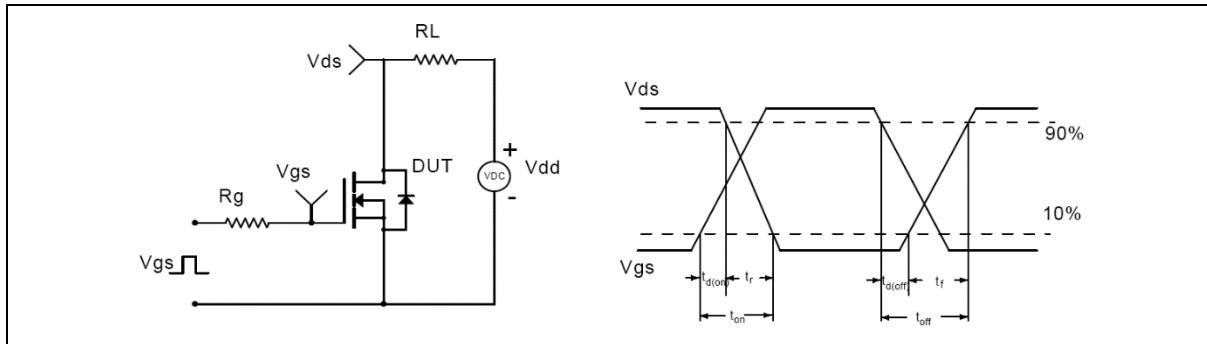
**Figure 6. Drain-source on-state resistance**



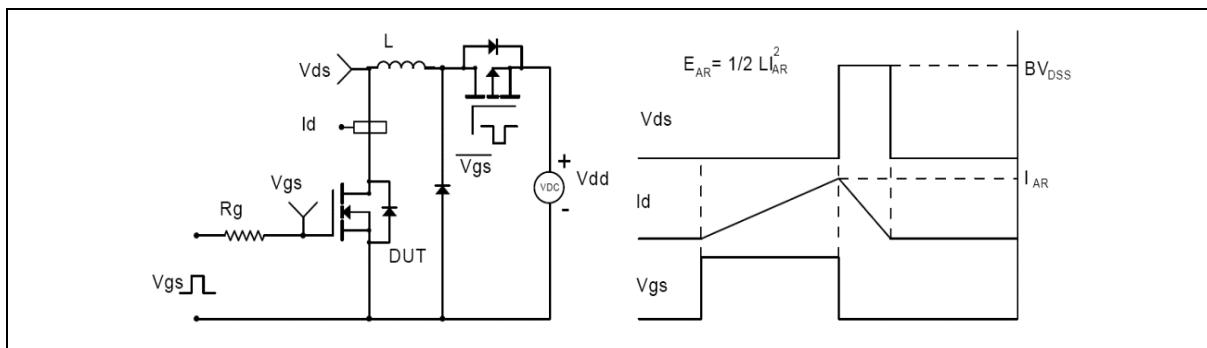
### Test circuits and waveforms



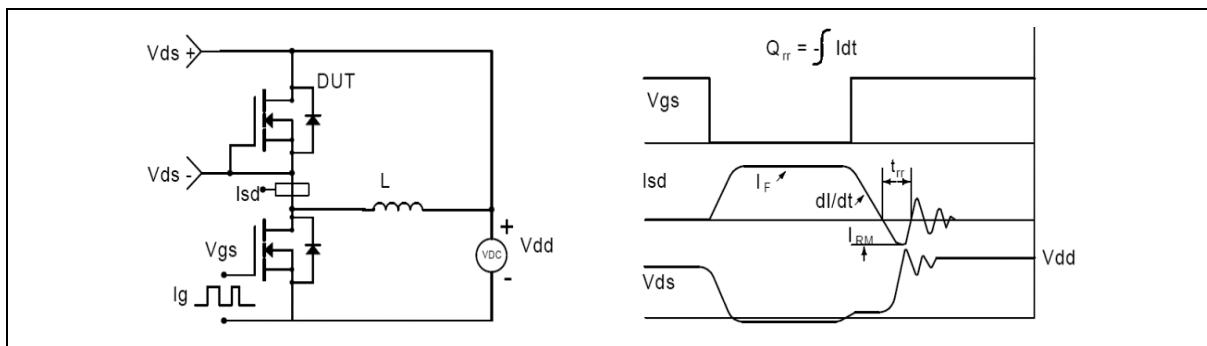
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

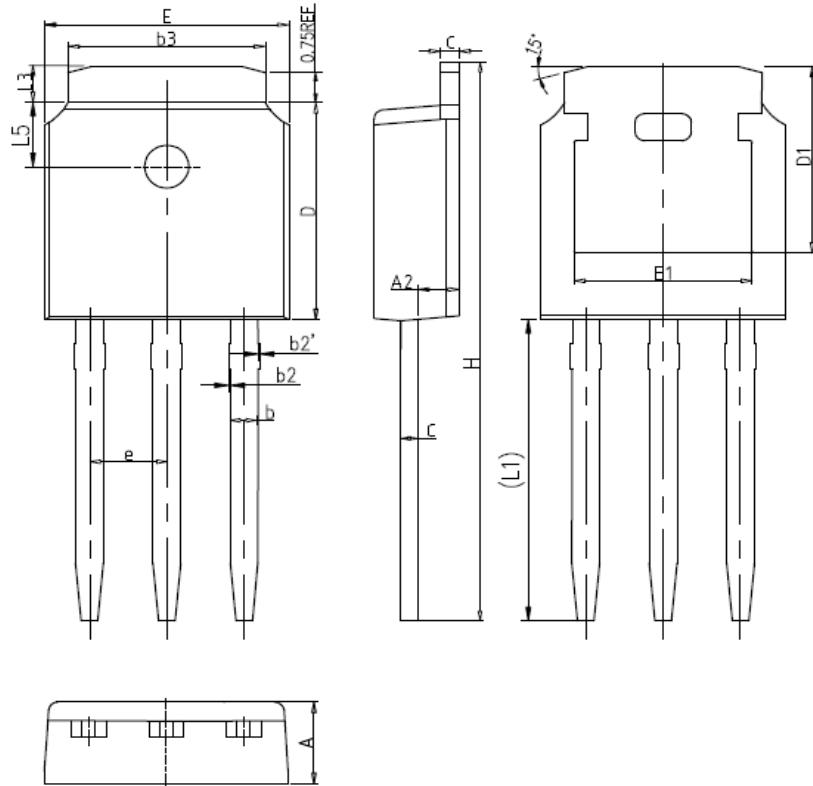


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

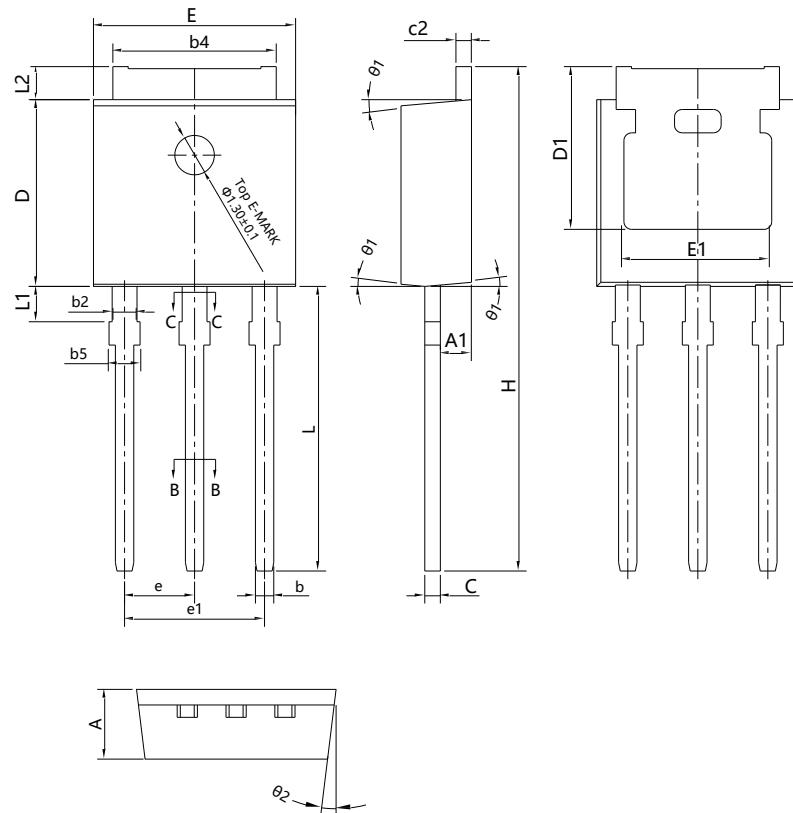
## Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.40
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
b2'	0.00	0.04	0.10
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.286BSC		
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

Version 1: TO251-C package outline dimension

## Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.35
A1	0.90	1.01	1.10
b	0.56	-	0.69
b1	0.55	0.60	0.65
b2	0.77	-	0.90
b3	0.76	0.81	0.86
b4	5.23	5.33	5.43
b5	-	-	1.05
c	0.46	-	0.59
c1	0.45	0.51	0.55
c2	0.46	-	0.59
D	6.00	6.10	6.20
D1	5.20	-	-
E	6.50	6.60	6.70
E1	4.60	4.83	5.00
e	2.24	2.29	2.34
e1	4.47	4.57	4.67
H	16.18	16.48	16.78
L	9.00	9.30	9.60
L1	0.95	1.16	1.35
L2	0.90	1.08	1.25
θ1	3°	5°	7°
θ2	1°	3°	5°

Version 2: TO251-J package outline dimension

## Ordering Information

Package Type	Units/Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO251-C	75	66	4950	6	29700
TO251-J	75	60	4500	5	22500

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG10R10AF	TO251	yes	yes	yes

## Legal Disclaimer

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